

ABSTRACT

A semiconductor module includes a substrate having opposite surfaces, a semiconductor device, and a plate-shaped lead. The semiconductor device is mounted on the substrate, and has opposite surfaces and electrodes. One of the opposite surfaces is disposed on the substrate. The electrodes are disposed on the other one of the opposite surfaces. The plate-shaped lead has an electrode joint joined to the electrodes, a wiring joint joined to a wiring unit disposed outside the semiconductor device, and a connector connecting the electrode joint and the wiring joint. At least the electrode joint includes a high thermal conductor, and a low expander disposed in the high thermal conductor. The semiconductor module is good in terms of the reliability and assembly easiness when wiring the electrodes of the semiconductor device.